

-2.8A

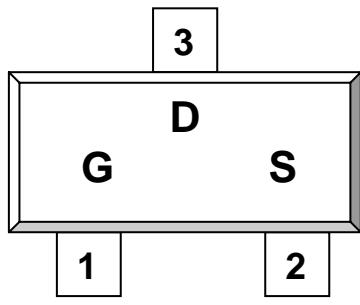
DESCRIPTION

The ST2301 is the P-Channel logic enhancement mode power field effect transistor are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other batter powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

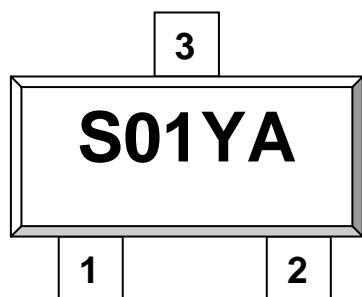
PIN CONFIGURATION SOT-23-3L



1.Gate 2.Source 3.Drain

FEATURE

- -20V/-2.8A, $R_{DS(ON)} = 120\text{m-ohm}$ @ $VGS = -4.5\text{V}$
- -20V/-2.0A, $R_{DS(ON)} = 170\text{m-ohm}$ @ $VGS = -2.5\text{V}$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23-3L package design



S: Subcontractor Y: Year Code A: Process Code



STANSON TECHNOLOGY

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P Channel Enhancement Mode MOSFET **ST2301**

-2.8A**ABSOULTE MAXIMUM RATINGS (Ta = 25 Unless otherwise noted)**

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V _{DSS}	-20	V
Gate-Source Voltage		V _{GSS}	+12	V
Continuous Drain Current (TJ=150)	T _A =25 T _A =70	I _D	-2.5 -1.5	A
Pulsed Drain Current		I _{DM}	-10	A
Continuous Source Current (Diode Conduction)		I _S	-1.6	A
Power Dissipation	T _A =25 T _A =70	P _D	1.25 0.8	W
Operation Junction Temperature		T _J	150	
Storage Temperature Range		T _{STG}	-55/150	
Thermal Resistance-Junction to Ambient		R _{JA}	120	/W

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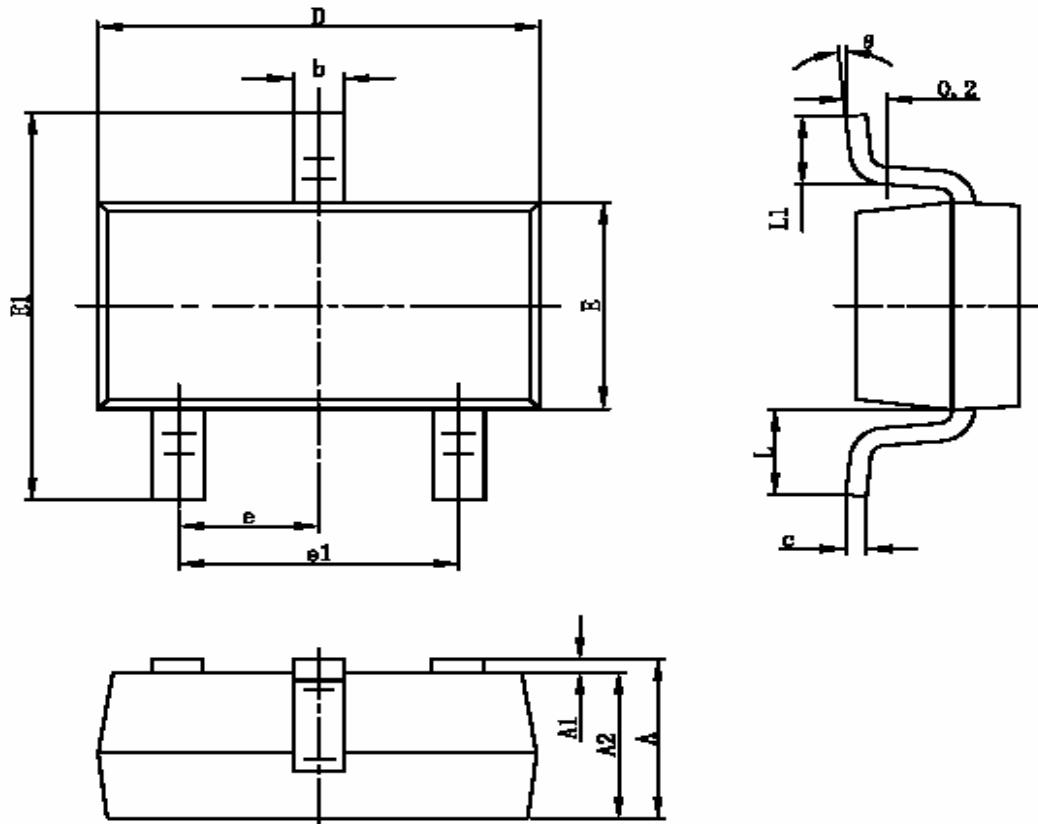
P Channel Enhancement Mode MOSFET**ST2301****-2.5A****ELECTRICAL CHARACTERISTICS (Ta = 25 Unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250uA	-20			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250uA	-0.45		-1.5	V
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =+8V			+100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V			-1	uA
		V _{DS} =-30V, V _{GS} =0V T _J =55			-10	
On-State Drain Current	I _{D(on)}	V _{DS} -5V, V _{GS} =-4.5V V _{DS} -5V, V _{GS} =-2.5V	-6 -3			A
Drain-source On-Resistance	R _{D(S)on}	V _{GS} =-4.5V, I _D =-2.8A V _{GS} =-2.5V, I _D =-2.0A		0.09 0.145	0.12 0.17	
Forward Transconductance	g _{fs}	V _{DS} =-5V, I _D =-2.8V		6.5		S
Diode Forward Voltage	V _{SD}	I _S =-1.6A, V _{GS} =0V		-0.8	-1.2	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =-6V, V _{GS} =-4.5V ID -2.8A		5.8	10	nC
Gate-Source Charge	Q _{gs}			0.85		
Gate-Drain Charge	Q _{gd}			1.7		
Input Capacitance	C _{iss}	V _{DS} =-6V, V _{GS} =0V F=1MHz		415		pF
Output Capacitance	C _{oss}			223		
Reverse Transfer Capacitance	C _{rss}			23		
Turn-On Time	t _{d(on)} t _r	V _{DD} =-6V, R _L =6 ID=-1A, V _{GEN} =-4.5V R _G =6		13	25	nS
Turn-Off Time	t _{d(off)} t _f			36	60	
				42	70	
				34	60	

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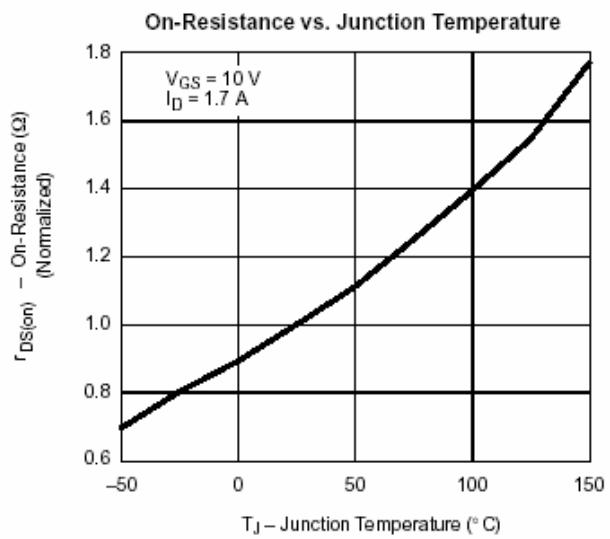
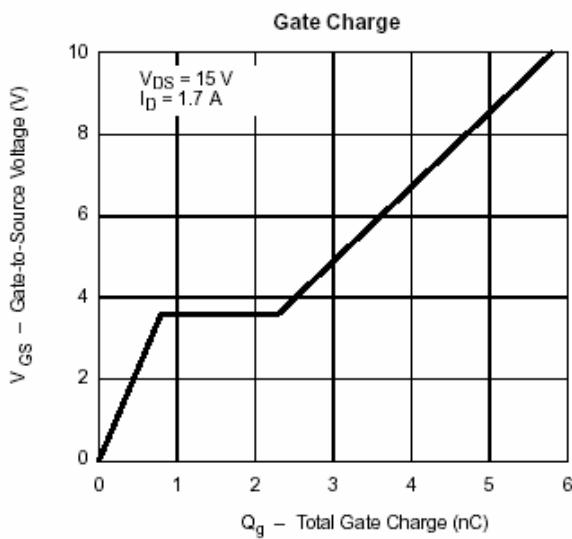
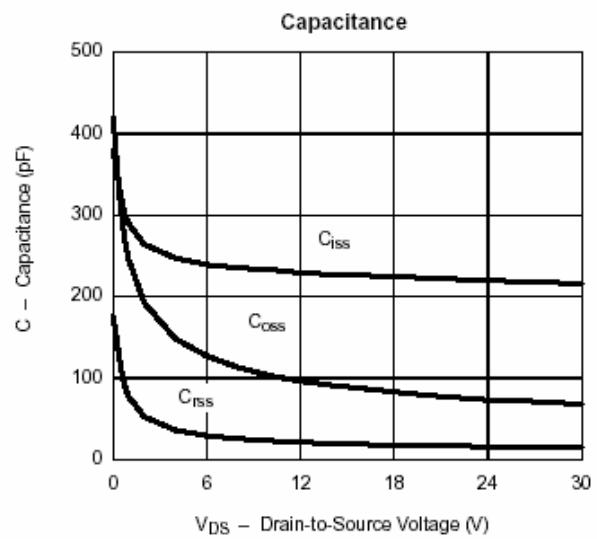
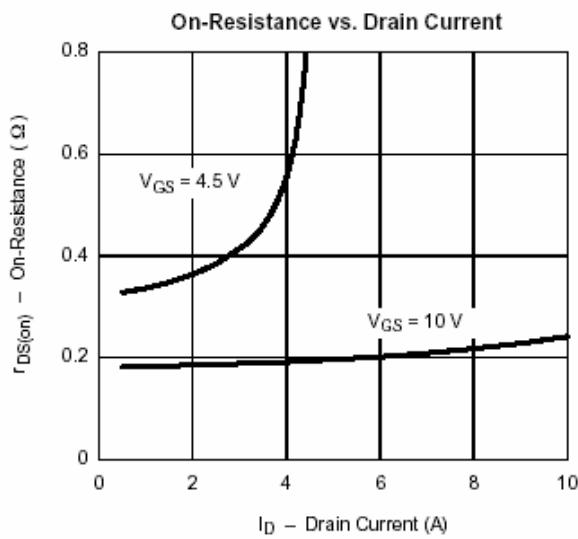
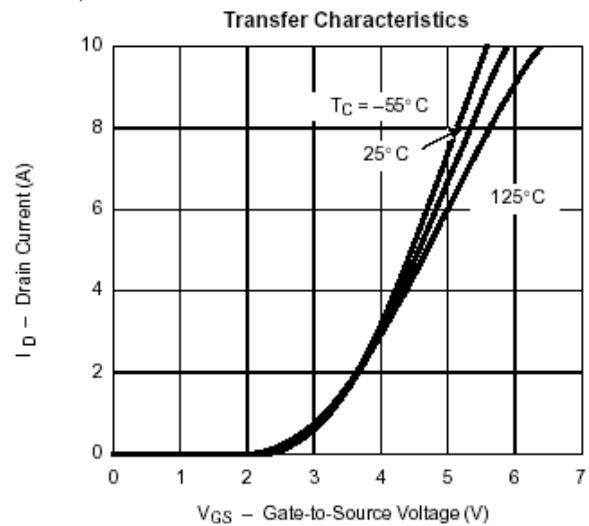
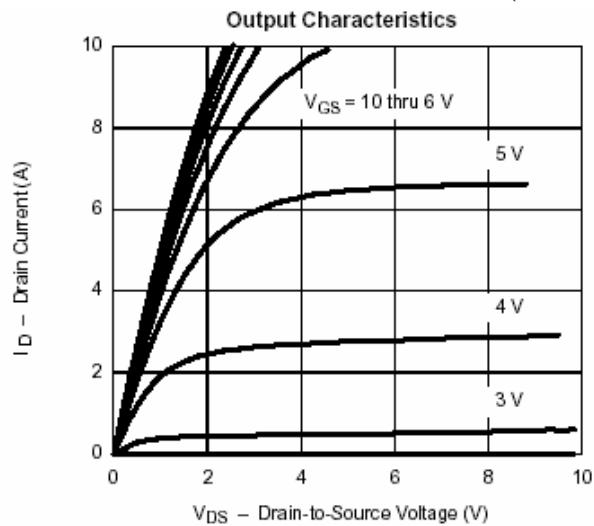
-2.5A**SOT-23-3L PACKAGE OUTLINE**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.400	0.012	0.016
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.700REF		0.028REF	
L1	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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